

**REMARKS**

In the above-identified Office Action claims 1, 2 and 4 have been rejected as being anticipated by the publication to Stewart et al. The Examiner has stated that a plastic adhesive can be applied to a surface mount electronic device facing printed circuit board providing a gap between the thermoplastic adhesive and the circuit board. However, Applicant notes that the Stewart et al. gap is between the substrate and the top of the printed circuit board, not between the adhesive sheet and the printed circuit board as recited in the claims. As such, Applicant believes that it recites over Stewart et al. and is patentable thereover.

Further, Claim 3 has been rejected as unpatentable over Stewart in view of Kumakura. The Examiner will note that Kumakura require a thermoset adhesive while Stewart et al. requires thermoplastic adhesive. In fact, Stewart et al. would not work with a thermoset adhesive because Stewart et al. requires his adhesive to soften sufficiently to flow across his gap. The thermoset adhesive of Kumakura would not soften. Thus it is not possible to combine the teachings with Kumakura and that of Stewart et al. and the rejection must fail.

Claim 5 has been rejected as unpatentable over Stewart et al. in view of Kumakura. For the above reason, Kumakura cannot be combined with Stewart et al. and thus this rejection must fail.

Claims 5 and 6 have been rejected under 35 U.S.C. section 103(a) in view of Applicant's admitted prior art. Claims 5 and 6 depend upon Claim 1 which is patentable pursuant to the arguments set forth above and thus Applicant believes that claims 5 and 6 should also be allowable.

Applicant hereby requests reconsideration and reexamination thereof.

With the above amendments and remarks, this application is considered ready for allowance and applicant earnestly solicits an early notice of same. Should the

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Examiner be of the opinion that a telephone conference would expedite prosecution of the subject application, he is respectfully requested to call the undersigned at the below listed number.

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Respectfully submitted,

A handwritten signature in black ink, appearing to read "Gerald T. Shekleton". The signature is fluid and cursive, with the first name "Gerald" being more prominent.

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**Gerald T Shekleton**

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